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### FDP7030BL/FDB7030BL

## N-Channel Logic Level PowerTrench<sup>O</sup> MOSFET

### **General Description**

This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

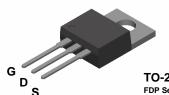
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable  $R_{\text{DS(ON)}}\text{specifications}.$ 

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

It has been optimized for low gate charge, low  $R_{\text{DS}(\text{ON})}$  and fast switching speed.

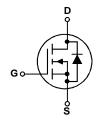
### **Features**

- 60 A, 30 V  $R_{DS(ON)} = 9 \text{ m}\Omega$  @  $V_{GS} = 10 \text{ V}$   $R_{DS(ON)} = 12 \text{ m}\Omega$  @  $V_{GS} = 4.5 \text{ V}$
- Critical DC electrical parameters specified at elevated temperature
- High performance trench technology for extremely low  $R_{\mbox{\scriptsize DS}(\mbox{\scriptsize ON})}$
- 175°C maximum junction temperature rating



**Absolute Maximum Ratings** 





TO-220 S TO-263AB FDP Series FDB Series

| Symbol                            | Parameter  |          | Ratings     | Units |  |
|-----------------------------------|--|----------|-------------|-------|--|
| V <sub>DSS</sub>                  | Drain-Source Voltage   |          | 30          | V     |  |
| V <sub>GSS</sub>                  | Gate-Source Voltage  |          | ± 20        | V     |  |
| I <sub>D</sub>                    | Drain Current - Continuous   | (Note 1) | 60          | А     |  |
|                                   | - Pulsed   | (Note 1) | 180         |       |  |
| P <sub>D</sub>                    | Total Power Dissipation @ T <sub>C</sub> = 25°C  Derate above 25°C |          | 60          | W     |  |
|                                   |  |          | 0.4         | W/°C  |  |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature Range                   |          | -65 to +175 | °C    |  |

T<sub>A</sub>=25°C unless otherwise noted

### **Thermal Characteristics**

| R <sub>θJC</sub> | Thermal Resistance, Junction-to-Case    | 2.5  | °C/W |
|------------------|---|------|------|
| $R_{\theta JA}$  | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W |

**Package Marking and Ordering Information** 

| Device Marking | Device    | Reel Size | Tape width | Quantity  |
|----------------|-----------|-----------|------------|-----------|
| FDB7030BL      | FDB7030BL | 13"       | 24mm       | 800 units |
| FDP7030BL      | FDP7030BL | Tube      | n/a        | 45        |

| Symbol                                 | Parameter   | Test Conditions   | Min      | Тур                | Max           | Units |
|--|---|---|----------|--------------------|---------------|-------|
| Drain-Sc                               | ource Avalanche Ratings (Note                     | 1)  |          | •                  |               | •     |
| W <sub>DSS</sub>                       | Single Pulse Drain-Source<br>Avalanche Energy     | $V_{DD} = 15 \text{ V}, \qquad I_{D} = 60 \text{ A}$  |          |                    | 73            | mJ    |
| I <sub>AR</sub>                        | Maximum Drain-Source Avalanche Current            |   |          |                    | 60            | Α     |
| Off Char                               | acteristics                                       |   | <u> </u> | ı                  | l .           | I     |
| BV <sub>DSS</sub>                      | Drain-Source Breakdown Voltage                    | $V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$  | 30       |                    |               | V     |
| ΔBV <sub>DSS</sub><br>ΔT <sub>J</sub>  | Breakdown Voltage Temperature Coefficient         | $I_D$ = 250 $\mu$ A, Referenced to 25°C   |          | 22                 |               | mV/°C |
| I <sub>DSS</sub>                       | Zero Gate Voltage Drain Current                   | $V_{DS} = 24 \text{ V}, \qquad V_{GS} = 0 \text{ V}$  |          |                    | 1             | μΑ    |
| I <sub>GSS</sub>                       | Gate-Body Leakage                                 | $V_{GS} = \pm 20 \text{ V},  V_{DS} = 0 \text{ V}$  |          |                    | ± 100         | nA    |
| On Char                                | acteristics (Note 2)                              |   |          |                    |               |       |
| V <sub>GS(th)</sub>                    | Gate Threshold Voltage                            | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$   | 1        | 1.9                | 3             | V     |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage<br>Temperature Coefficient | $I_D$ = 250 $\mu$ A, Referenced to 25°C   |          | -5                 |               | mV/°C |
| R <sub>DS(on)</sub>                    | Static Drain–Source On–<br>Resistance             | $V_{GS} = 10 \text{ V}, \qquad I_D = 30 \text{ A}$ $V_{GS} = 4.5 \text{ V}, \qquad I_D = 25 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 125^{\circ}\text{C}$ |          | 6.8<br>8.5<br>10.1 | 9<br>12<br>18 | mΩ    |
| I <sub>D(on)</sub>                     | On-State Drain Current                            | $V_{GS} = 10 \text{ V}, \qquad V_{DS} = 10 \text{ V}$   | 30       |                    |               | Α     |
| <b>g</b> FS                            | Forward Transconductance                          | $V_{DS} = 10V$ , $I_{D} = 30 \text{ A}$   |          | 85                 |               | S     |
|  | Characteristics                                   | 1   |          | l.                 |               | I     |
| C <sub>iss</sub>                       | Input Capacitance                                 | $V_{DS} = 15 \text{ V},  V_{GS} = 0 \text{ V},$   |          | 1760               |               | pF    |
| Coss                                   | Output Capacitance                                | f = 1.0 MHz   |          | 440                |               | pF    |
| C <sub>rss</sub>                       | Reverse Transfer Capacitance                      | 1   |          | 185                |               | pF    |
| R <sub>G</sub>                         | Gate Resistance                                   | V <sub>GS</sub> = 15 mV, f = 1.0 MHz  |          | 1.2                |               | Ω     |
| Switchin                               | g Characteristics (Note 2)                        |   | •        | •                  |               |       |
| t <sub>d(on)</sub>                     | Turn-On Delay Time                                | $V_{DD} = 15V$ , $I_{D} = 1 A$ ,  |          | 12                 | 22            | ns    |
| t <sub>r</sub>                         | Turn-On Rise Time                                 | $V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$  |          | 12                 | 22            | ns    |
| $t_{d(off)}$                           | Turn-Off Delay Time                               | 1   |          | 30                 | 48            | ns    |
| t <sub>f</sub>                         | Turn-Off Fall Time                                |   |          | 19                 | 33            | ns    |
| Q <sub>g</sub>                         | Total Gate Charge                                 | $V_{DS} = 15 \text{ V}, \qquad I_{D} = 30 \text{ A},$   |          | 17                 | 24            | nC    |
| Q <sub>gs</sub>                        | Gate-Source Charge                                | $V_{GS} = 5 V$  |          | 5.4                |               | nC    |
| $Q_{gd}$                               | Gate-Drain Charge                                 | 1   |          | 6.4                |               | nC    |
|  | ource Diode Characteristics                       | and Maximum Ratings   |          | •                  |               |       |
| I <sub>s</sub>                         | Maximum Continuous Drain–Source                   |   |          |                    | 60            | Α     |
| V <sub>SD</sub>                        | Drain-Source Diode Forward<br>Voltage             | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 30 A (Note 1)   |          | 0.92               | 1.3           | V     |
| t <sub>rr</sub>                        | Diode Reverse Recovery Time                       | I <sub>F</sub> = 30 A,  |          |                    | 30            | nS    |
| Q <sub>rr</sub>                        | Diode Reverse Recovery Charge                     | $d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$  |          |                    | 20            | nC    |

#### Notes

<sup>1.</sup> Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

### **Typical Characteristics**

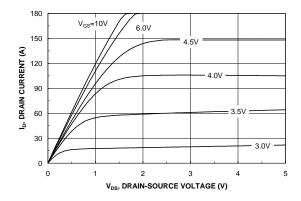


Figure 1. On-Region Characteristics.

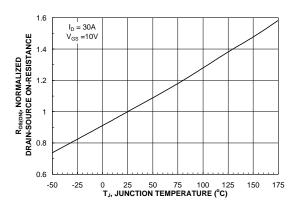


Figure 3. On-Resistance Variation with Temperature.

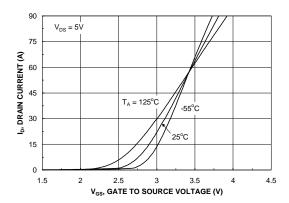


Figure 5. Transfer Characteristics.

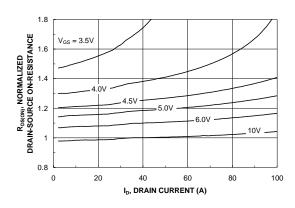


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

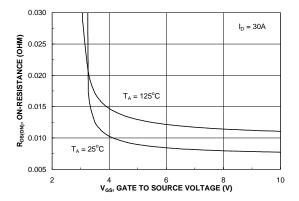


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

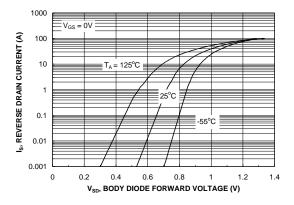
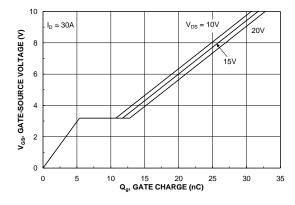


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

### **Typical Characteristics**



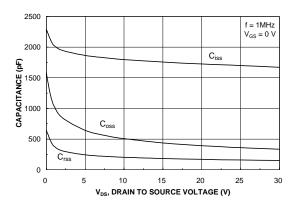
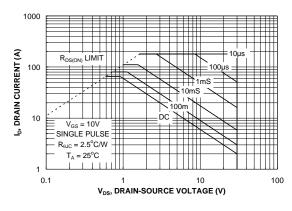


Figure 7. Gate Charge Characteristics.





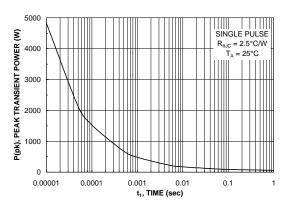


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

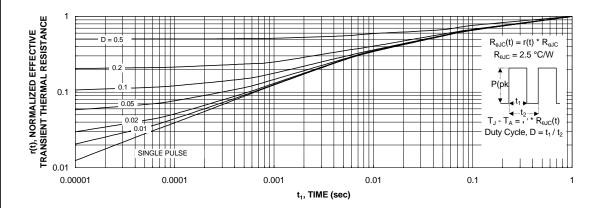


Figure 11. Transient Thermal Response Curve.

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